



06-02-2006



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U.S. Department of Commerce  
Patent and Trademark Office

Form PTO-1595

OMB No. 0651-0011 (exp. 4/94)

To the Honorable Commissioner of Patents and Trade

the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Ralf Siemieniec  
Hans-Joachim Schulze  
Franz Hirler

## 2. Name and address of receiving party(ies):

Name: Infinion Technologies Austria AG  
Street Address: Siemensstrasse 2  
City: 9500 Villach  
Country: Austria

Additional name(s) of conveying party(ies) attached? [ ] Yes [X] No

Additional name(s) &amp; address(es) attached? [ ] Yes [X] No

## 3. Nature of Conveyance:

☒ Assignment      ☐ Merger  
☐ Security Agreement      ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date(s): 03/24/06; 05/04/06; 03/26/06

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is

A. Patent Application No(s) 11/364,882

B. Patent No(s)

Additional numbers attached? [ ] Yes [X] No

Title of Invention: Method for Producing a Buried Semiconductor LayerOur Docket No.: 1890-0357

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Harold C. MooreInternal Address: Maginot, Moore & BeckStreet Address: 111 Monument Circle, Suite 3250  
City: State: Zip: Indianapolis, IN 46204-5109

## 6. Total number of applications and patents involved

17. Total fee (37 CFR 3.41): \$. 40.00☒ Enclosed  
☐ Authorized to be charged to deposit account8. Deposit Account number: 13-0014

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Harold C. MooreName of Person Signing  
Registration No. 37,892[Signature]  
SignatureMay 24, 2006

Date

Total number of pages including cover sheet, attachments and document 4

Mail documents to be recorded with required cover sheet information to:  
Mail Stop Assignment Recordation Services, Commissioner for Patents  
P.O. Box 1450, Alexandria, VA 22313-145005/30/2006 SSITHIB1 00000062 11364882  
01 FC:8021

40.00 DP

PATENT  
REEL: 017930 FRAME: 0475

INFINEON REF NO.13.921  
MMB REF NO.1890-0357**ASSIGNMENT**

For good and valuable consideration, I, Ralf Siemieniec, a citizen of Germany, residing at Litzelhofenstr. 8, 9500 Villach, Austria, Hans-Joachim Schulze, a citizen of Germany, residing at Ottostr. 60f, 85521 Ottobrunn, Germany, and Franz Hirler, a citizen of Germany, residing at Mozartstr. 4, 84424 Isen, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies Austria AG, a corporation organized and existing under the laws of Austria, having its principal place of business at Siemensstrasse 2, 9500 Villach, Austria, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, Serial No. 11/364.882, filed on February 28, 2006 and

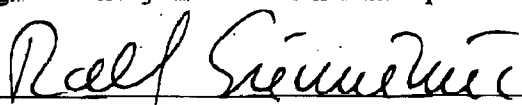
entitled: **METHOD FOR PRODUCING A BURIED SEMICONDUCTOR LAYER**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: \_\_\_\_\_

DATE: 24.03.2006

NAME: Ralf Siemieniec

SIGNATURE: \_\_\_\_\_

DATE: \_\_\_\_\_

NAME: Hans-Joachim Schulze

SIGNATURE: \_\_\_\_\_

DATE: \_\_\_\_\_

NAME: Franz Hirler

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Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

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SIGNATURE: \_\_\_\_\_

DATE: \_\_\_\_\_

NAME: Ralf Siemieniec

SIGNATURE: \_\_\_\_\_

DATE: 4.5.06

NAME: Hans-Joachim Schulze

SIGNATURE: \_\_\_\_\_

DATE: \_\_\_\_\_

NAME: Franz Hirler

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SIGNATURE: \_\_\_\_\_

DATE: \_\_\_\_\_

NAME: Ralf Siemieniec

SIGNATURE: \_\_\_\_\_

DATE: \_\_\_\_\_

NAME: Hans-Joachim Schulze

SIGNATURE: \_\_\_\_\_

DATE: 2006-03-26

NAME: Franz Hirler

**PATENT****RECORDED: 05/26/2006****REEL: 017930 FRAME: 0478**